P＋N-Channel Enhancement Mode MOSFET

TGBLH4409-5DL8

Features

- Low on-resistance
- Green device available
- RoHS compliant with Halogen-free
- Qualified to AEC-Q101 Standards

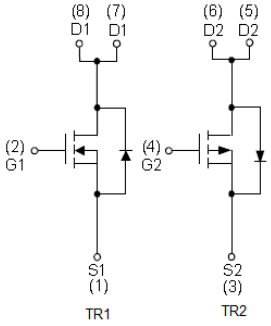
HF

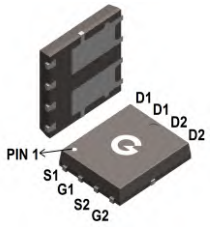
Applications

- Synchronous Rectification
- Motor Control
- Portable equipment application

Mechanical Data

- Case: PDFN5×6-8LC
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208





PDFN5×6-8LC

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
TGBLH4409-5DL8	PDFN5×6-8LC	5000 pcs / Tape & Reel	GBLH4409

Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Symbol	TR1	TR2	Unit
Drain-to-Source Voltage	V_{DSS}	40	-40	V
Gate-to-Source Voltage	V_{GSS}	±20	±20	V
Continuous Drain Current (T_C = 25°C)	I_D	56	-40	A
Continuous Drain Current (T_C = 100°C)		40	-28	A
Continuous Drain Current (T_A = 25°C) *1		16	-10	A
Continuous Drain Current (T_A = 100°C) *1		11	-7	A
Single Pulse Avalanche Energy *3	E_{AS}	18	60	mJ
Pulsed Drain Current (t_p = 10μs, T_C = 25°C)	I_{DM}	224	-160	A
Power Dissipation (T_C = 25°C)	P_D	47		W
Operating Junction Temperature Range	T_J	-55 ~ +175		°C
Storage Temperature Range	T_{STG}	-55 ~ +175		°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	3.2	°C/W
Thermal Resistance Junction-to-Air *1	$R_{\theta JA}$	-	-	40	°C/W

Electrical Characteristics-TR1 (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 40V, V_{GS} = 0V	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA
On Characteristics						
$R_{DS(ON)}$	Drain-Source On-resistance *2	V_{GS} = 10V,I_D = 12A	-	8	9	mΩ
		V_{GS} = 4.5V,I_D = 10A	-	13	16	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	1.5	1.7	2.5	V
		V_{DS} = V_{GS}, I_D = 25μA	1.2	1.5	2.2	V
R_G	Gate Resistance	V_{GS} = 0V, f = 1MHz	-	3	-	Ω
Dynamic Characteristics						
C_{ISS}	Input Capacitance	V_{GS} = 0V V_{DS} = 15V f = 1.0MHz	-	687	-	pF
C_{OSS}	Output Capacitance		-	135	-	
C_{RSS}	Reverse Transfer Capacitance		-	128	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time	V_{DD} = 20V V_{GS} = 15V R_G = 3.3Ω I_D = 15A	-	5	-	ns
t_r	Turn-on Rise Time		-	26	-	
$t_{d(OFF)}$	Turn-Off Delay Time		-	29	-	
t_f	Turn-Off Fall Time		-	11	-	
Q_G	Total Gate-Charge	V_{DD} = 20V V_{GS} = 4.5V I_D = 12A	-	11.3	-	nC
Q_{GS}	Gate to Source Charge		-	3.5	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	5.6	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage *2	I_{SD} = 10A, V_{GS} = 0V	-	0.83	1	V
trr	Reverse Recovery Time	I_F = 15A, V_{GS} = 0V di/dt = 100A/μs	-	43	-	ns
Qrr	Reverse Recovery Charge		-	19	-	nC

Electrical Characteristics-TR2 (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = -250μA	-40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -32V, V_{GS} = 0V	-	-	-1	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA
On Characteristics						
$R_{DS(ON)}$	Drain-Source On-resistance *2	V_{GS} = -10V, I_D = -15A	-	16	20	mΩ
		V_{GS} = -4.5V, I_D = -10A	-	21	30	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = -250μA	-1.5	-1.9	-3	V
		V_{DS} = V_{GS}, I_D = -25μA	-1.2	-1.7	-2.5	V
Dynamic Characteristics						
C_{ISS}	Input Capacitance	V_{GS} = 0V V_{DS} = -20V f = 1.0MHz	-	2450	-	pF
C_{OSS}	Output Capacitance		-	184	-	
C_{RSS}	Reverse Transfer Capacitance		-	171	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time *4	V_{DD} = -20V V_{GS} = -10V R_L = 1.6Ω I_D = -1A	-	10	-	ns
t_r	Turn-on Rise Time *4		-	24	-	
$t_{d(OFF)}$	Turn-Off Delay Time *4		-	40	-	
t_f	Turn-Off Fall Time *4		-	9	-	
Q_G	Total Gate-Charge	V_{DD} = -20V V_{GS} = -10V I_D = -15A	-	56.5	-	nC
Q_{GS}	Gate to Source Charge		-	8.5	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	11.1	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage *2	I_{SD} = -15A, V_{GS} = 0V	-	-0.9	-1.2	V
trr	Reverse Recovery Time	I_F = -15A, V_{GS} = 0V di/dt = 100A/μs	-	40	-	ns
Qrr	Reverse Recovery Charge		-	34	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
3. The E_{AS} data shows Max. rating. N: The test condition is V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH
   P: The test condition is V_{DD} = -20V, V_{GS} = -10V, L = 0.5mH
4. Guaranteed by design, not subject to production

Ratings and Characteristics Curves-TR1 (@ T_A = 25°C unless otherwise specified)

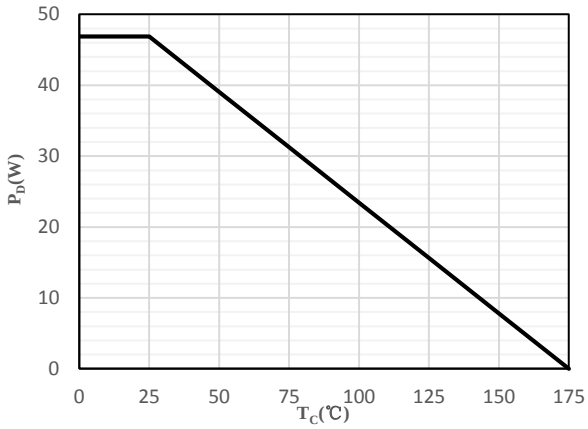


Fig 1 Power Dissipation

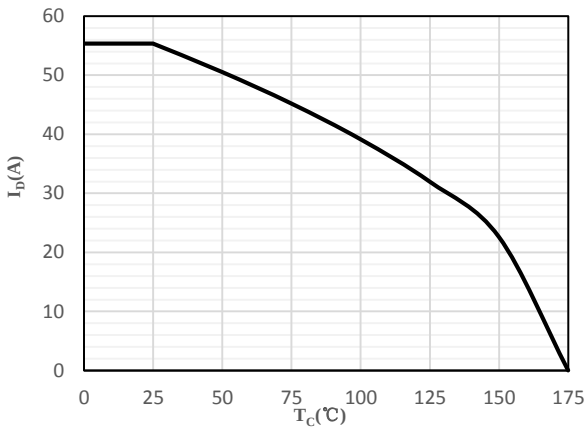


Fig 2 Drain Current

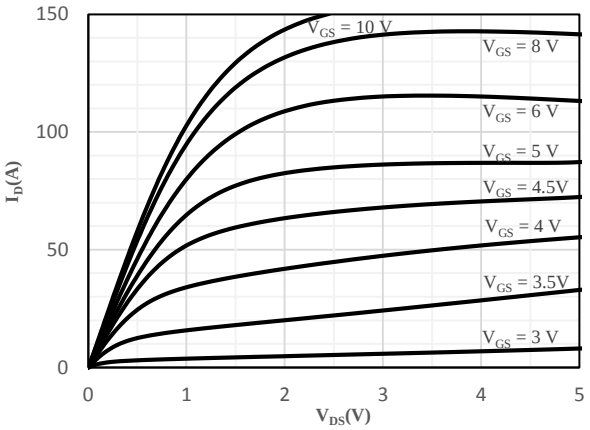


Fig 3 Typical Output Characteristics

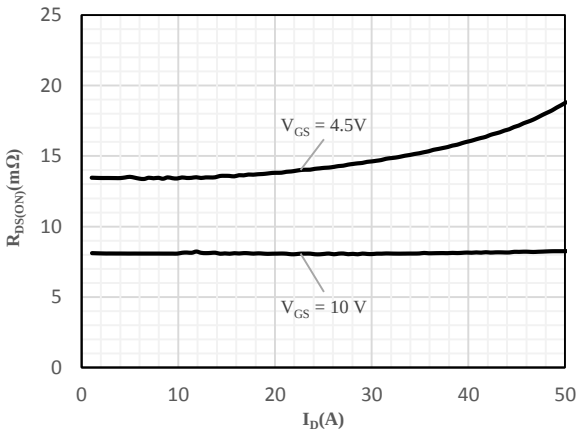


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

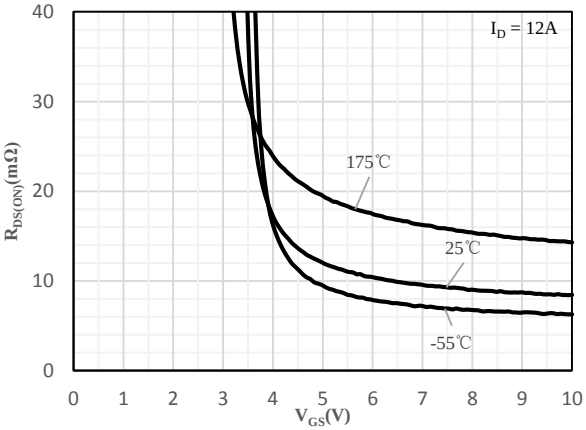


Fig 5 On-Resistance vs. Gate-Source Voltage

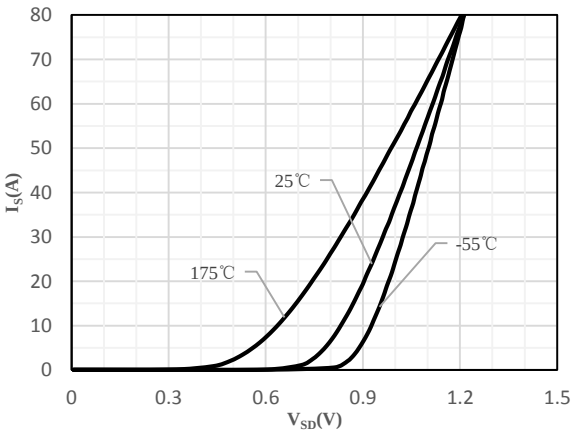


Fig 6 Body-Diode Characteristics

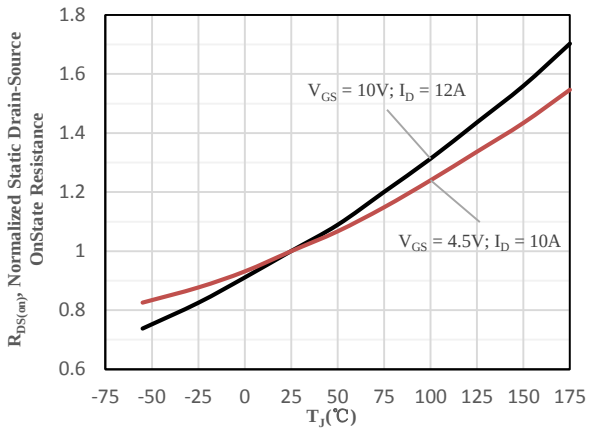


Fig 7 Normalized On-Resistance vs. Junction Temperature

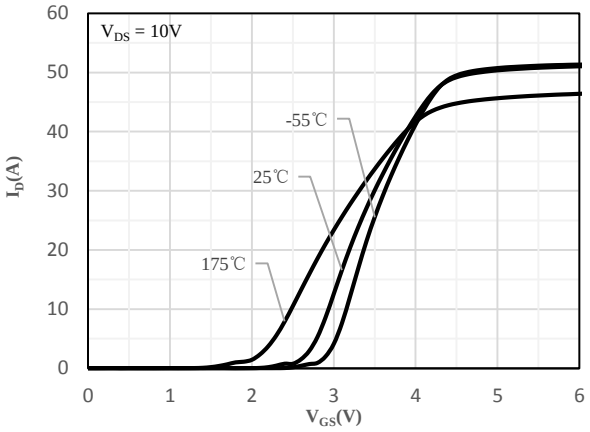


Fig 8 Transfer Characteristics

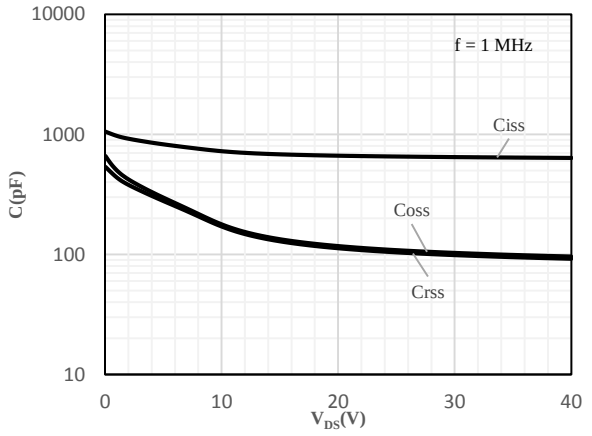


Fig 9 Capacitance Characteristics

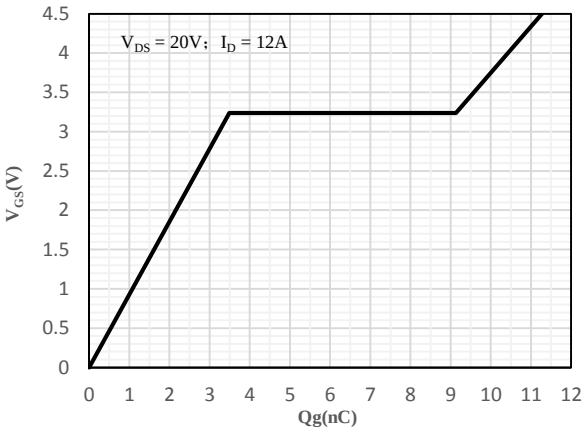


Fig 10 Gate-Charge Characteristics

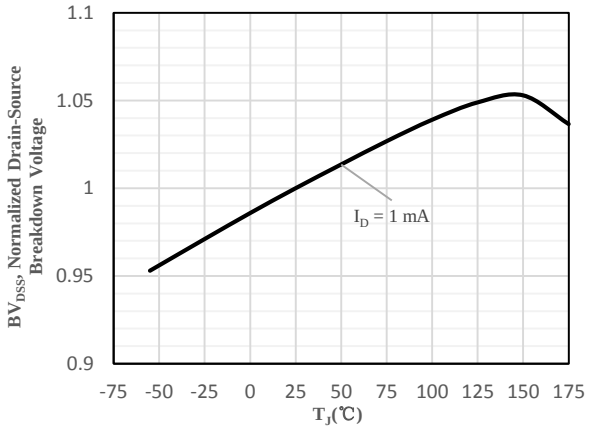


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

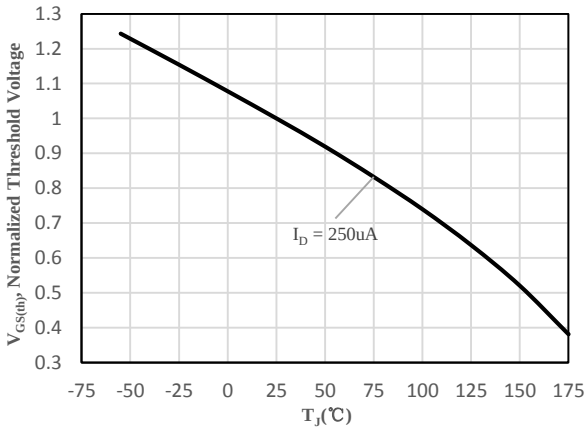


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

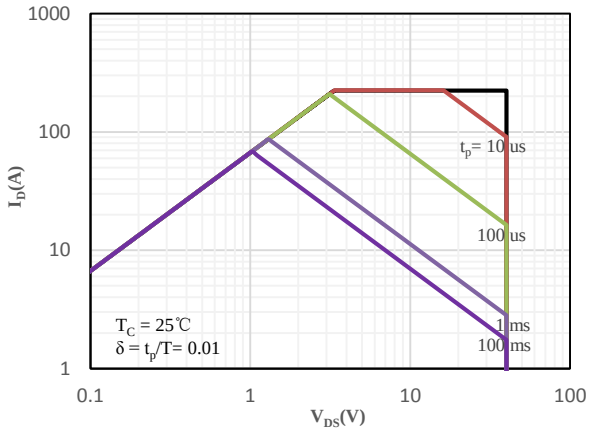


Fig 13 Safe Operating Area

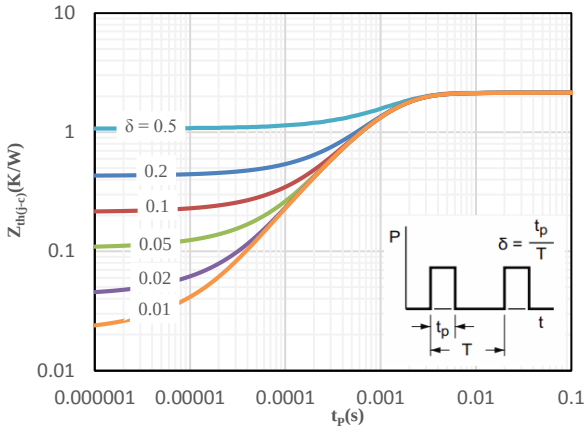


Fig 14 Maximum transient thermal impedance

Ratings and Characteristics Curves-TR2 (@ T_A = 25°C unless otherwise specified)

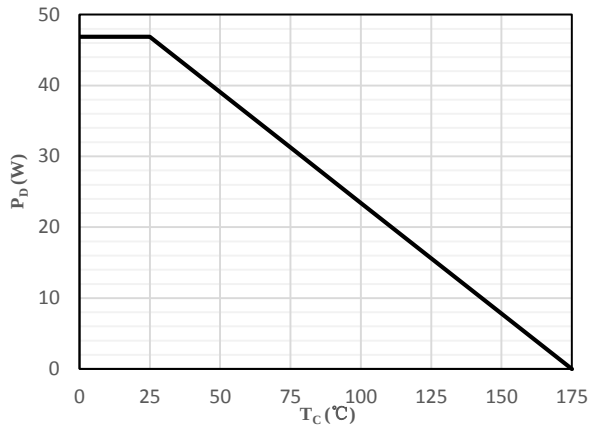


Fig 1 Power Dissipation

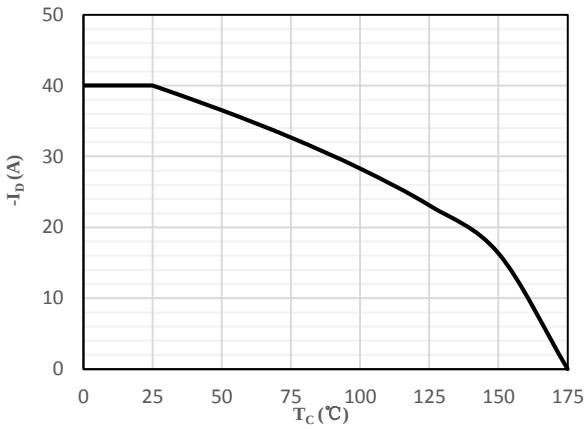


Fig 2 Drain Current

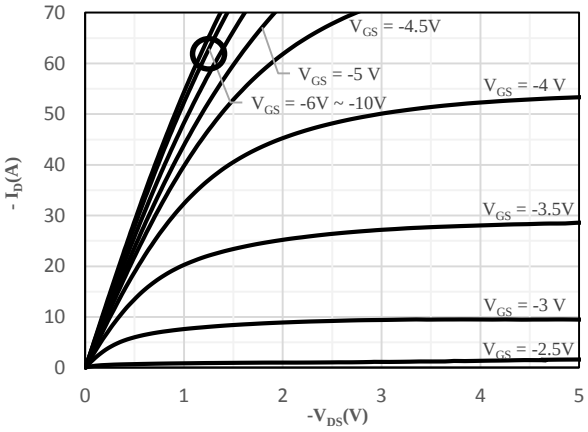


Fig 3 Typical Output Characteristics

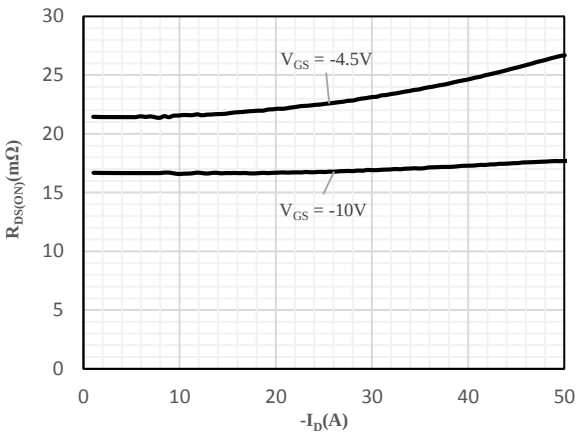


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

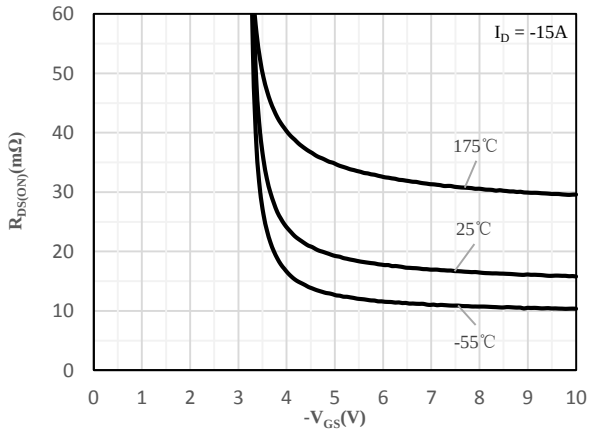


Fig 5 On-Resistance vs. Gate-Source Voltage

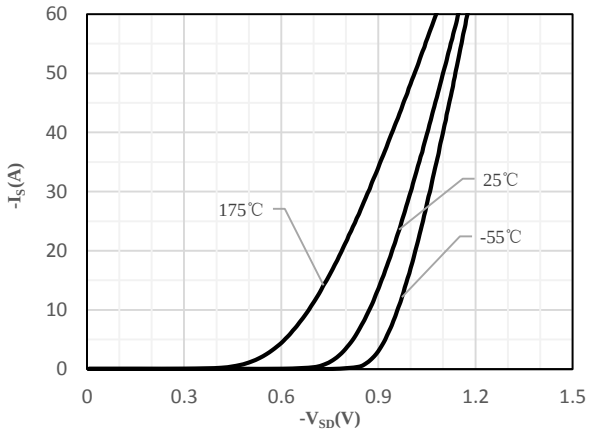


Fig 6 Body-Diode Characteristics

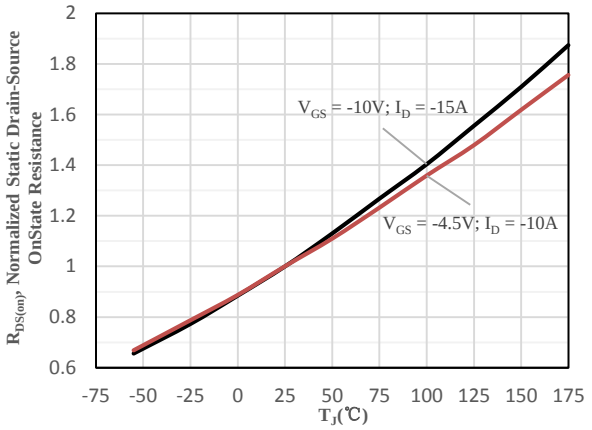


Fig 7 Normalized On-Resistance vs. Junction Temperature

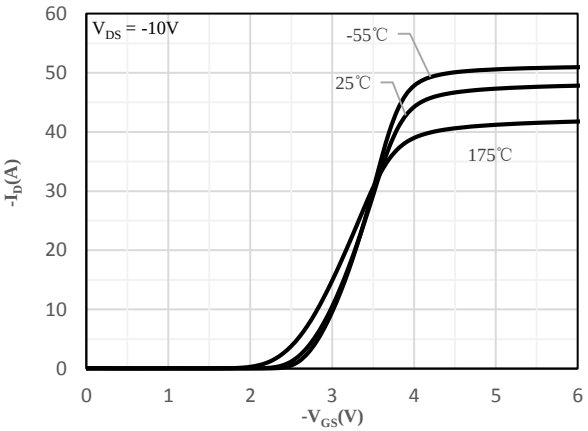


Fig 8 Transfer Characteristics

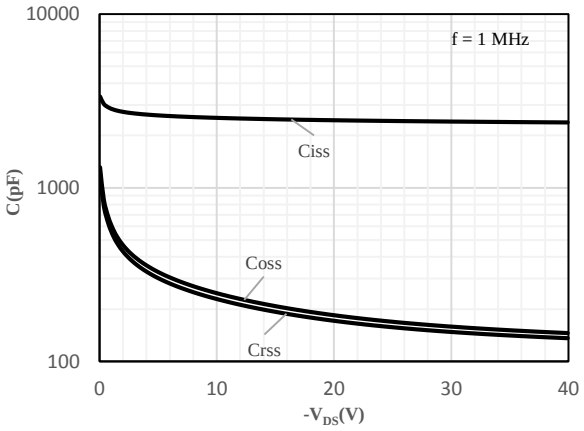


Fig 9 Capacitance Characteristics

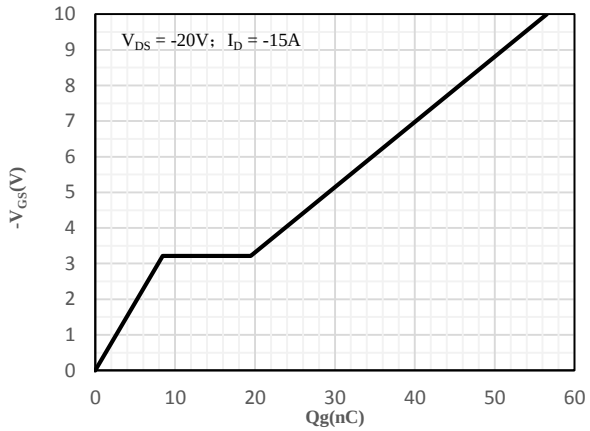


Fig 10 Gate-Charge Characteristics

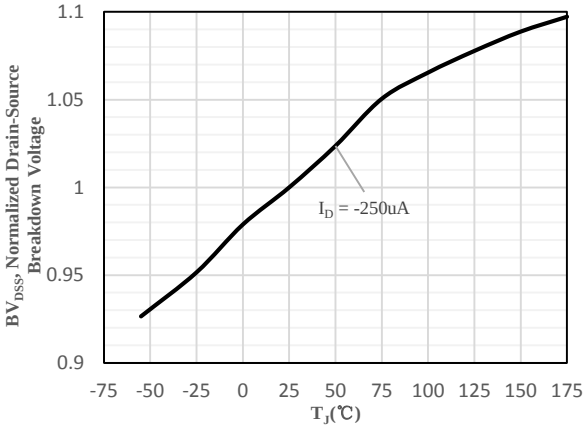


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

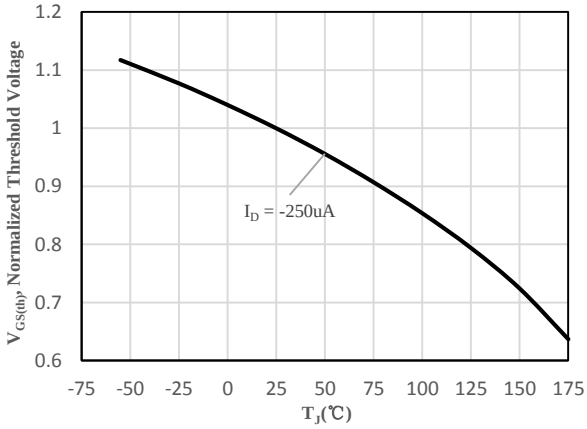


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

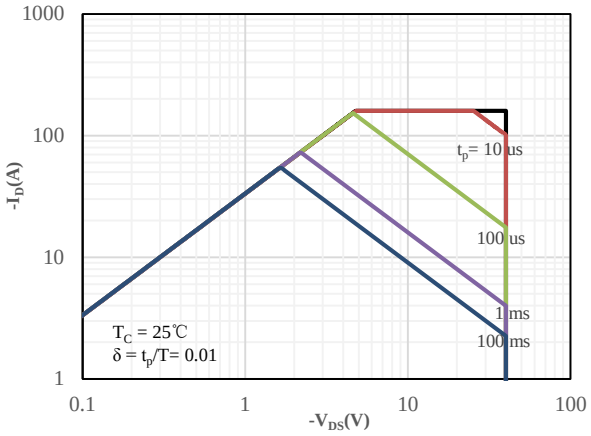


Fig 13 Safe Operating Area

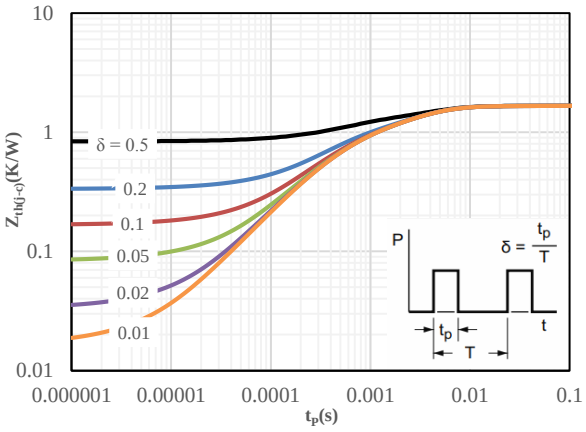
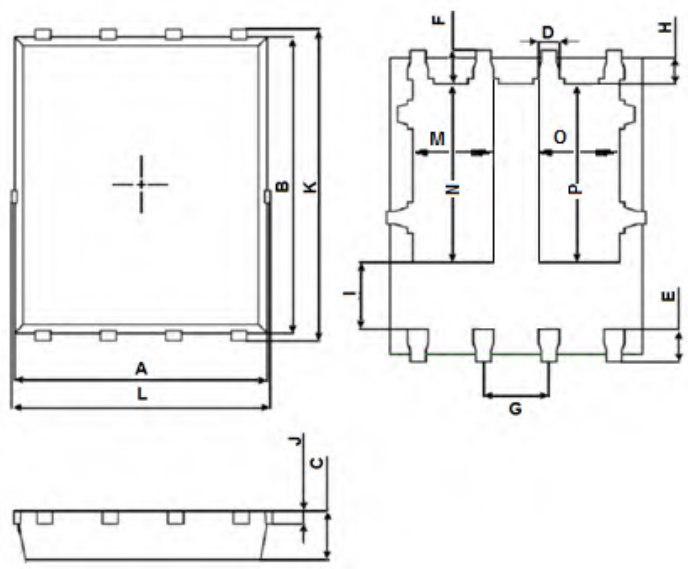


Fig 14 Maximum transient thermal impedance

Package Outline Dimensions (Unit: mm)



PDFN5×6-8LC		
Dimension	**Min.**	**Max.**
A	4.824	4.976
B	5.674	5.826
C	0.900	1.000
D	0.350	0.450
E	0.559	0.711
F	0.574	0.726
G	1.250	1.290
H	0.424	0.576
I	1.190	1.390
J	0.154	0.354
K	5.974	6.126
L	4.944	5.096
M/O	1.595	1.795
N/P	3.375	3.575

Mounting Pad Layout (Unit: mm)

PDFN5×6-8LC